

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-40V	10mΩ@-10V	-30A
	13mΩ@-4.5V	

Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

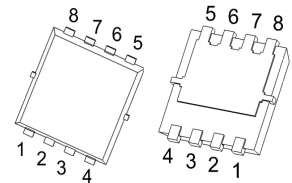
- Power Switching Application

MARKING:

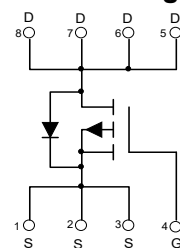


M110P4L = Device Code
 XX = Date Code
 Solid Dot = Green Indicator

PDFN3.3×3.3-8L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	-40	V
Gate - Source Voltage	V_{GS}	±20	V
Continuous Drain Current ¹	I_D	-30	A
Pulsed Drain Current ²	I_{DM}	-120	A
Single Pulsed Avalanche Current ³	I_{AS}	-28	A
Single Pulsed Avalanche Energy ³	E_{AS}	392	mJ
Power Dissipation ⁵	P_D	21	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	64	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	6	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

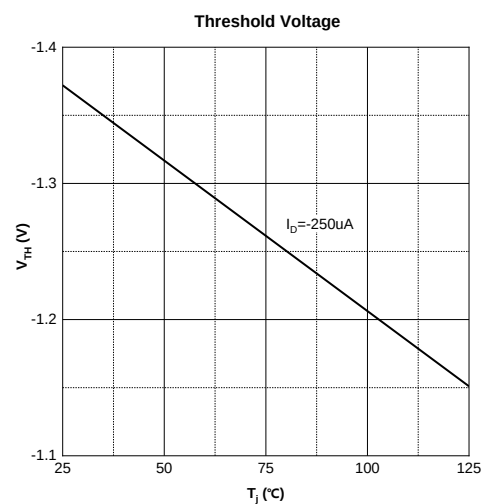
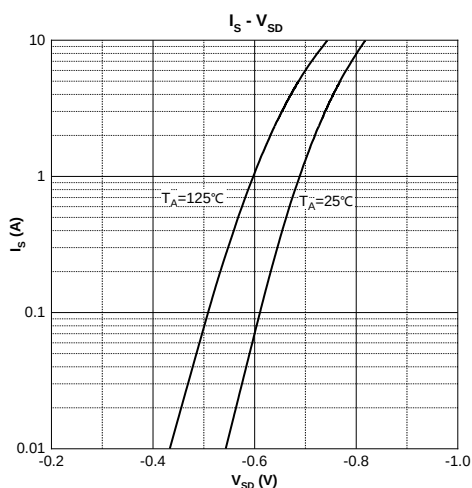
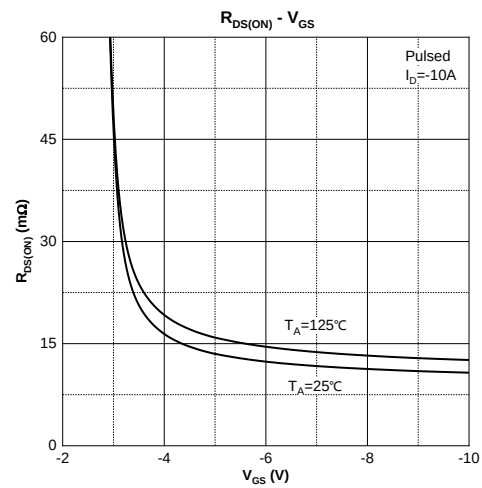
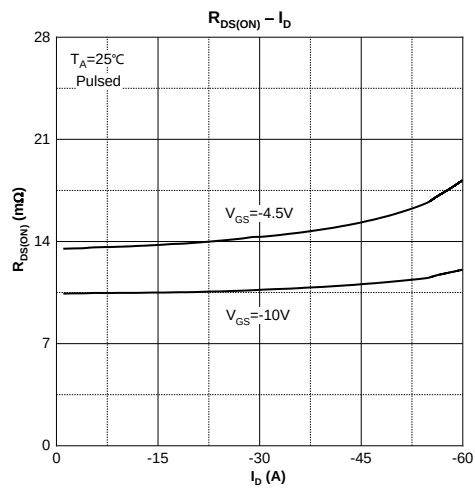
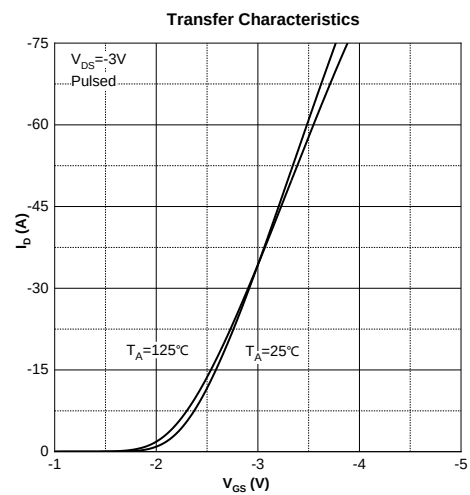
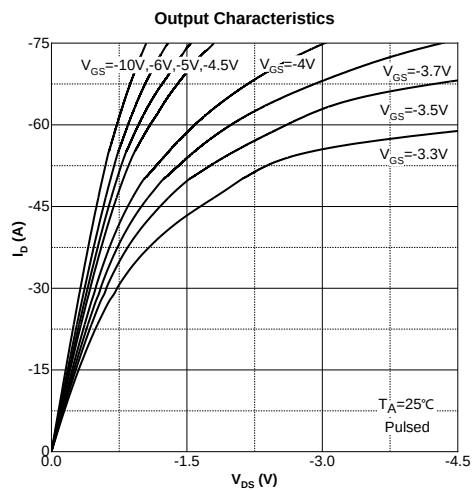
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V			-1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics ⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.4	-3.0	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -18A		10	13	mΩ
		V _{GS} = -4.5V, I _D = -12A		13	20	
Forward Transconductance	g _{FS}	V _{DS} = -10V, I _D = -18A		36		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = -20V, V _{GS} = 0V, f = 1MHz		2716		pF
Output Capacitance	C _{oss}			267		
Reverse Transfer Capacitance	C _{rss}			245		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		8.7		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = -20V, V _{GS} = -10V, I _D = -12A		57		nC
Gate-source Charge	Q _{gs}			7.0		
Gate-drain Charge	Q _{gd}			12.2		
Turn-on Delay Time	t _{d(on)}	V _{DD} = -15V, V _{GS} = -10V, I _D = -18A, R _G = 3Ω		33		ns
Turn-on Rise Time	t _r			28		
Turn-off Delay Ttime	t _{d(off)}			85		
Turn-off Fall Time	t _f			9		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = -1A			-1.2	V

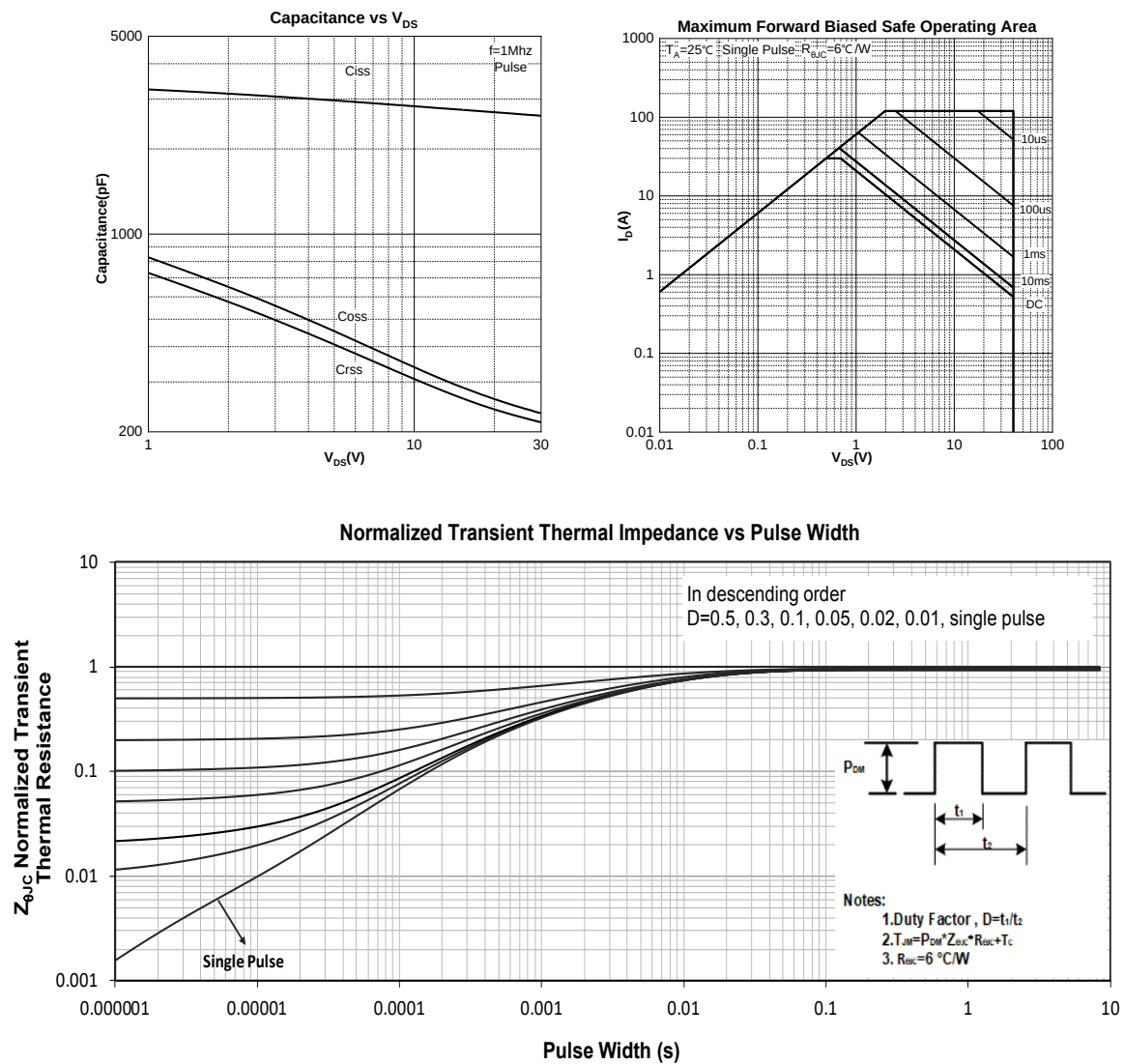
Notes :

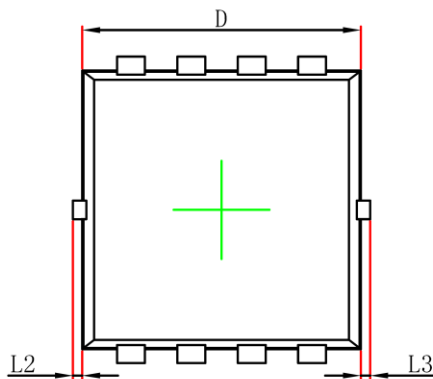
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = -20V, V_{GS} = -10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics

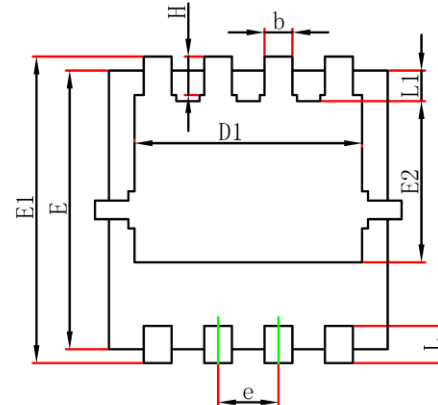


Typical Characteristics

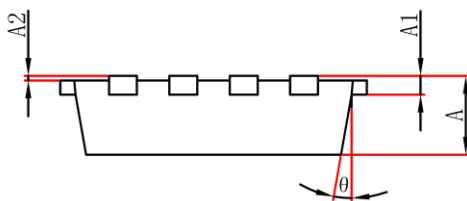


PDFN3.3×3.3-8L Package Information


Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°